ABSTRACT

METHOD OF COMPRESSION MOLDING FOR ELECTRONIC PART AND APPARATUS THEREFOR

First, a given amount of granular resin (6) is fed into a resin accommodation space (22) of plate (21). Secondly, the plate (21) is covered with a mold release film (11) so as to spread over the resin accommodation space (22). Thirdly, the resin accommodation space (22) is set to a given degree of vacuum. Fourthly, the plate (21) covered with the mold release film (11) is turned upside down. Finally, the plate turned upside down is moved into a cavity (5), so that the surface of the cavity (5) is covered with the mold release film (11). In this situation, the granular resin (6) is caused to fall from the resin accommodation space (22) into the cavity (5) covered with the mold release film (11).

FIG. 5